

**Glass Passivated Bridge Rectifiers****Features**

- Glass passivated chip
- Low forward voltage drop
- Ideal for printed circuit board
- Meet UL flammability classification 94V-0

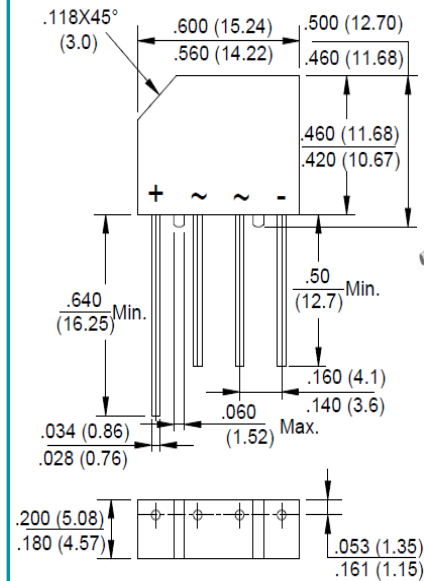
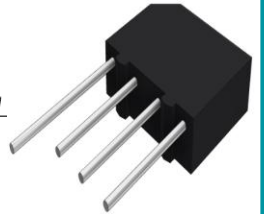
Mechanical Data

- Polarity: Symbol marked on body
- Mounting position: Any

Note: Products with logo  or  are made by HY Electronic (Cayman) Limited.

Applications

- General purpose use in AC/DC bridge full wave rectification, for home appliances, office equipment, etc.

Reverse Voltage - 50 to 1000 Volts**Forward Current - 2.0 Amperes****KBP****RoHS
COMPLIANT**

Package Outline Dimensions in Inches (Millimeters)

Maximum Ratings and Electrical Characteristics

Rating at 25°C ambient temperature unless otherwise specified.

Single phase, half wave, 60Hz, resistive or inductive load.

For capacitive load, derate current by 20%.

Characteristic	Symbol	KBP 2005G	KBP 201G	KBP 202G	KBP 204G	KBP 206G	KBP 208G	KBP 210G	Unit
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS Voltage	V_{RMS}	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	V_{DC}	50	100	200	400	600	800	1000	V
Maximum Average Forward Rectified Current @ $T_A=50^\circ\text{C}$	$I_{(AV)}$	2.0							A
Peak Forward Surge Current, 8.3ms Single Half Sine-Wave, Superimposed on Rated Load (JEDEC Method)	I_{FSM}	60							A
I^2t Rating for Fusing ($t < 8.3\text{ms}$)	I^2t	14.9							A^2s
Peak Forward Voltage per Diode at 2.0A DC	V_F	1.1							V
Maximum DC Reverse Current at Rated @ $T_J=25^\circ\text{C}$	I_R	10							μA
DC Blocking Voltage per Diode @ $T_J=100^\circ\text{C}$		1.0							mA
Operating Junction Temperature Range	T_J	-55 to +150							$^\circ\text{C}$
Storage Temperature Range	T_{STG}	-55 to +150							$^\circ\text{C}$



Fig. 1 - Forward Current Derating Curve

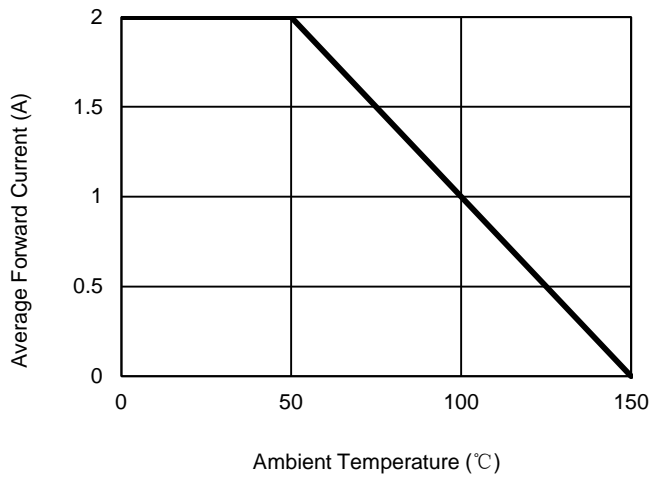


Fig. 2 - Maximum Non-Repetitive Surge Current

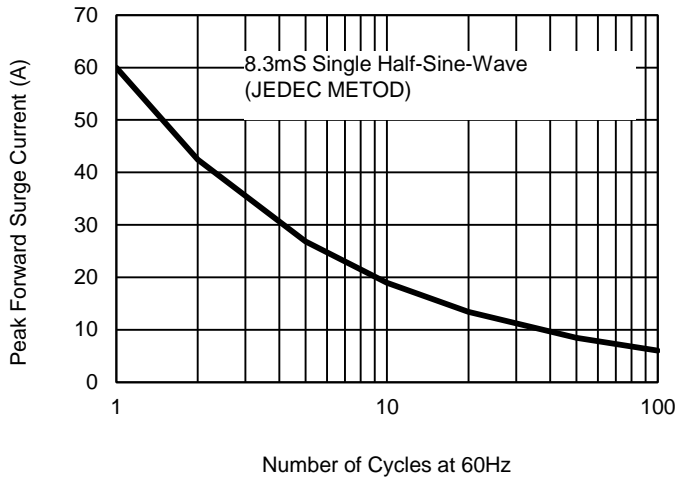


Fig. 3 - Typical Reverse Characteristics

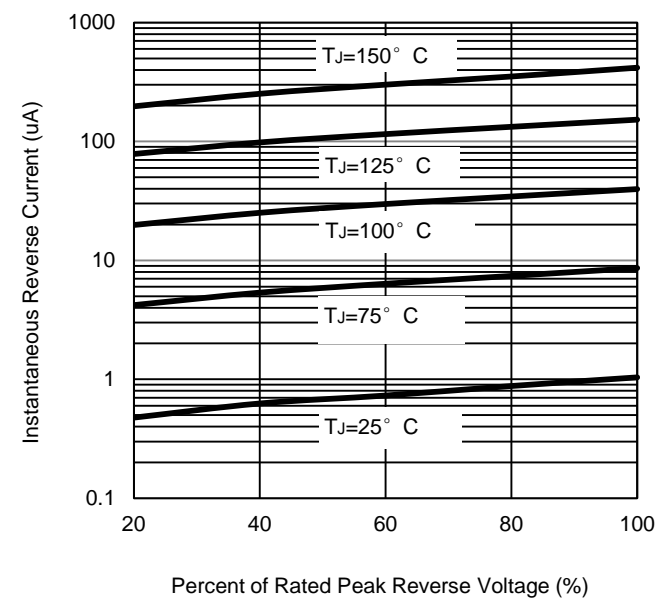
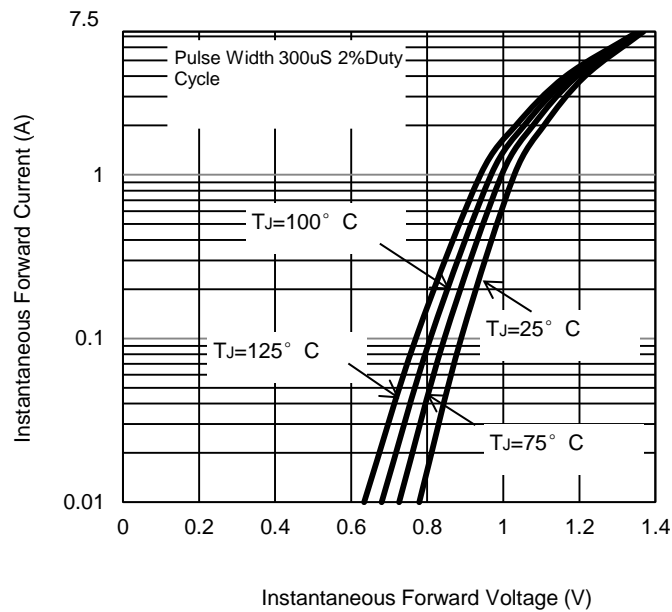


Fig. 4 - Typical Forward Characteristics



The curve above is for reference only.



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